

## **HPAD:** Sensors



## Next step for Sensors

- · Agree on sensor specifications
- Design sensor + test structures + test programme
- · Order (together with other projects?)

parameter	value	comments
dimensions	x·x mm <sup>2</sup>	mounting, test experiments
thickness	500-700 μm	U <sub>dep</sub> , plasma effects, shielding, efficiency, science
material/diode type	p <sup>+</sup> on n	h-collection, plasma effects, pulse shape
doping	3-5 kΩ·cm	U <sub>dep</sub> , plasma effects
doping uniformity		charge collection distortions
pixel dimensions	200·200 μm	electronics, science
$ m U_{max}$	1000 V	mounting, pulse shape, dead space at edges
pad layout		bump bonding, capacitance
biasing scheme		detector tests
coupling type	DC	bias current correction
inter-pixel capacitance		noise, cross-talk, avalanche breakdown, U <sub>operation</sub>
total dark current	2 μΑ	detector technology ok
max. dark current/pixel	50 nA	noise, uniformity
passivation	$SiO_2$ , $(Si_3N_4)$	irradiation, environmental effects
dead region at edges		dead space for science